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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16ce625-04e-so

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Name	DIP/ SOIC Pin #	SSOP Pin #	l/O/P Type	Buffer Type	Description
OSC1/CLKIN	16	18	I	ST/CMOS	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	17	0	-	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
MCLR/Vpp	4	4	I/P	ST	Master clear (reset) input/programming voltage input. This pin is an active low reset to the device.
					PORTA is a bi-directional I/O port.
RA0/AN0	17	19	I/O	ST	Analog comparator input
RA1/AN1	18	20	I/O	ST	Analog comparator input
RA2/AN2/VREF	1	1	I/O	ST	Analog comparator input or VREF output
RA3/AN3	2	2	I/O	ST	Analog comparator input /output
RA4/T0CKI	3	3	I/O	ST	Can be selected to be the clock input to the Timer0 timer/counter or a comparator output. Output is open drain type.
					PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT	6	7	I/O	TTL/ST(1)	RB0/INT can also be selected as an external interrupt pin.
RB1	7	8	I/O	TTL	
RB2	8	9	I/O	TTL	
RB3	9	10	I/O	TTL	
RB4	10	11	I/O	TTL	Interrupt on change pin.
RB5	11	12	I/O	TTL	Interrupt on change pin.
RB6	12	13	I/O	TTL/ST <sup>(2)</sup>	Interrupt on change pin. Serial programming clock.
RB7	13	14	I/O	TTL/ST <sup>(2)</sup>	Interrupt on change pin. Serial programming data.
Vss	5	5,6	Р	l –	Ground reference for logic and I/O pins.
Vdd	14	15,16	Р	—	Positive supply for logic and I/O pins.
Legend:		utput Not used : TTL inpu	1 :	O = input/or = Input	utput P = power ST = Schmitt Trigger input

**TABLE 3-1: PIC16CE62X PINOUT DESCRIPTION** 

**Note 1:** This buffer is a Schmitt Trigger input when configured as the external interrupt. **Note 2:** This buffer is a Schmitt Trigger input when used in serial programming mode.

### 4.2 Data Memory Organization

The data memory (Figure 4-4 and Figure 4-5) is partitioned into two Banks which contain the General Purpose Registers and the Special Function Registers. Bank 0 is selected when the RP0 bit is cleared. Bank 1 is selected when the RP0 bit (STATUS <5>) is set. The Special Function Registers are located in the first 32 locations of each Bank. Register locations 20-7Fh (Bank0) on the PIC16CE623/624 and 20-7Fh (Bank0) and A0-BFh (Bank1) on the PIC16CE625 are General Purpose Registers implemented as static RAM. Some special purpose registers are mapped in Bank 1. In all three microcontrollers, address space F0h-FFh (Bank1) is mapped to 70-7Fh (Bank0) as common RAM.

#### 4.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as  $96 \times 8$  in the PIC16CE623/624 and 128 x 8 in the PIC16CE625. Each is accessed either directly or indirectly through the File Select Register FSR (Section 4.4).

#### FIGURE 4-4: DATA MEMORY MAP FOR THE PIC16CE623/624

File Address	3	-	File Address		
00h	INDF <sup>(1)</sup>	INDF <sup>(1)</sup>	80h		
01h	TMR0	OPTION	81h		
02h	PCL	PCL	82h		
03h	STATUS	STATUS	83h		
04h	FSR	FSR	84h		
05h	PORTA	TRISA	85h		
06h	PORTB	TRISB	86h		
07h			87h		
08h			88h		
09h			89h		
0Ah	PCLATH	PCLATH	8Ah		
0Bh	INTCON	INTCON	8Bh		
0Ch	PIR1	PIE1	8Ch		
0Dh			8Dh		
0Eh		PCON	8Eh		
0Fh			8Fh		
10h		EEINTF	90h		
11h			91h		
12h			92h		
13h			93h		
14h			94h		
15h			95h		
16h			96h		
17h			97h		
18h			98h		
19h			99h		
1Ah			9Ah		
1Bh			9Bh		
1Ch			9Ch		
1Dh			9Dh		
1Eh			9Eh		
1Fh	CMCON	VRCON	9Fh		
20h			A0h		
	General Purpose Register				
			EFh		
		Accesses	F0h		
7Fh		70h-7Fh	FFh		
/ [1]	Bank 0	Bank 1			
	Unimplemented data memory locations, read as '0'. <b>Note 1:</b> Not a physical register.				

#### FIGURE 4-5: DATA MEMORY MAP FOR THE PIC16CE625

File			File
Address	;		Address
00h	INDF <sup>(1)</sup>	INDF <sup>(1)</sup>	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h		EEINTF	90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh			9Eh
1Fh	CMCON	VRCON	9Fh
20h			A0h
	General	General	AUII
	Purpose Register	Purpose Register	
	negistei	negister	BFh
			C0h
		_	F0h
		Accesses	
751		70h-7Fh	FFh
7Fh I	Bank 0	Bank 1	J FFN
<b>—</b>			
	plemented data me		ad as '0'.
Note 1:	Not a physical regis	ster.	

#### 4.2.2.2 OPTION REGISTER

The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the external RB0/INT interrupt, TMR0 and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for TMR0, assign the prescaler to the WDT (PSA = 1).

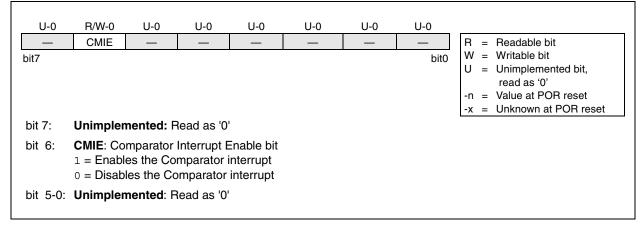
# REGISTER 4-2: OPTION REGISTER (ADDRESS 81H)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	
RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	R = Readable bit
bit7							bitO	W = Writable bit U = Unimplemented bit, read as '0' -n = Value at POR reset -x = Unknown at POR reset
bit 7:	<b>RBPU</b> : PO 1 = PORTE 0 = PORTE	3 pull-ups	are disal	oled	lividual port	latch valu	es	
bit 6:	INTEDG: In 1 = Interrup 0 = Interrup	ot on rising	g edge o	f RB0/INT				
bit 5:	<b>TOCS</b> : TMF 1 = Transiti 0 = Interna	ion on RA	4/T0CKI	pin	(OUT)			
bit 4:	bit 4: <b>T0SE</b> : TMR0 Source Edge Select bit 1 = Increment on high-to-low transition on RA4/T0CKI pin 0 = Increment on low-to-high transition on RA4/T0CKI pin							
bit 3:								
bit 2-0:	<b>PS&lt;2:0&gt;</b> : F	Prescaler I	Rate Sele	ect bits				
	Bit Value	TMR0 Ra	te WD1	Γ Rate				
	000 001 010 011 100 101 110 111	1:2 1:4 1:8 1:16 1:32 1:64 1:128 1:256	1 : 3 1 :	2 4				

#### 4.2.2.4 PIE1 REGISTER

This register contains the individual enable bit for the comparator interrupt.

### REGISTER 4-4: PIE1 REGISTER (ADDRESS 8CH)

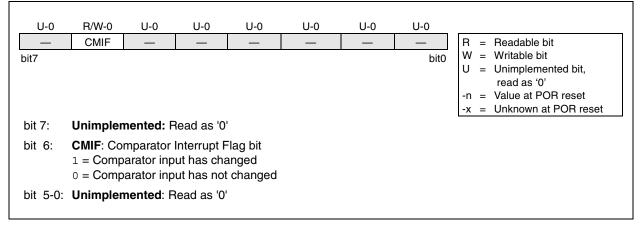


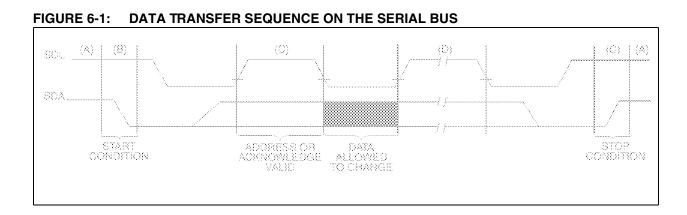
#### 4.2.2.5 PIR1 REGISTER

This register contains the individual flag bit for the comparator interrupt.

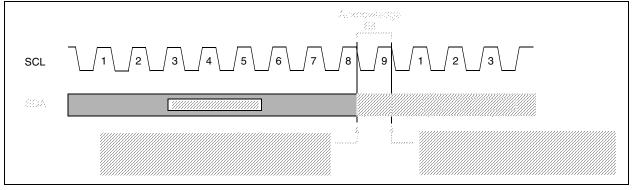
Note:	Interrupt flag bits get set when an interrupt				
	condition occurs, regardless of the state of				
	its corresponding enable bit or the global				
	enable bit, GIE (INTCON<7>). User				
	software should ensure the appropriate				
	interrupt flag bits are clear prior to enabling				
	an interrupt.				

### REGISTER 4-5: PIR1 REGISTER (ADDRESS 0CH)







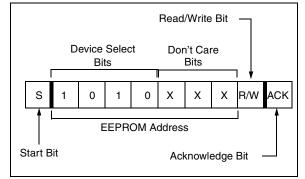


### 6.2 Device Addressing

After generating a START condition, the processor transmits a control byte consisting of a EEPROM address and a Read/Write bit that indicates what type of operation is to be performed. The EEPROM address consists of a 4-bit device code (1010) followed by three don't care bits.

The last bit of the control byte determines the operation to be performed. When set to a one, a read operation is selected, and when set to a zero, a write operation is selected. (Figure 6-3). The bus is monitored for its corresponding EEPROM address all the time. It generates an acknowledge bit if the EEPROM address was true and it is not in a programming mode.

### FIGURE 6-3: CONTROL BYTE FORMAT



# 7.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
- Interrupt on overflow from FFh to 00h
- Edge select for external clock

Figure 7-1 is a simplified block diagram of the Timer0 module.

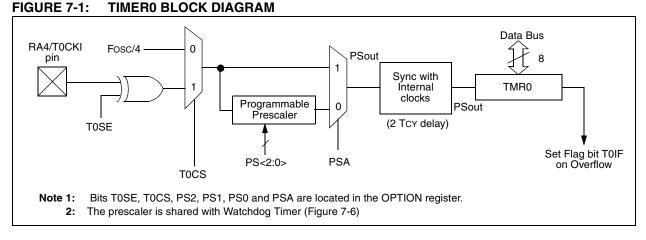
Timer mode is selected by clearing the TOCS bit (OPTION<5>). In timer mode, the TMR0 will increment every instruction cycle (without prescaler). If Timer0 is written, the increment is inhibited for the following two cycles (Figure 7-2 and Figure 7-3). The user can work around this by writing an adjusted value to TMR0.

Counter mode is selected by setting the T0CS bit. In this mode Timer0 will increment either on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the source edge (T0SE) control bit (OPTION<4>). Clearing the TOSE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 7.2.

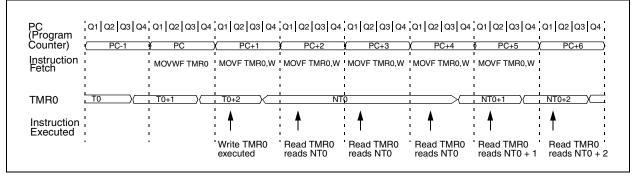
The prescaler is shared between the Timer0 module and the Watchdog Timer. The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale value of 1:2, 1:4, ..., 1:256 are selectable. Section 7.3 details the operation of the prescaler.

### 7.1 <u>Timer0 Interrupt</u>

Timer0 interrupt is generated when the TMR0 register timer/counter overflows from FFh to 00h. This overflow sets the T0IF bit. The interrupt can be masked by clearing the T0IE bit (INTCON<5>). The T0IF bit (INTCON<2>) must be cleared in software by the Timer0 module interrupt service routine before re-enabling this interrupt. The Timer0 interrupt cannot wake the processor from SLEEP since the timer is shut off during SLEEP. See Figure 7-4 for Timer0 interrupt timing.



### FIGURE 7-2: TIMER0 (TMR0) TIMING: INTERNAL CLOCK/NO PRESCALER



The code example in Example 8-1 depicts the steps required to configure the comparator module. RA3 and RA4 are configured as digital output. RA0 and RA1 are configured as the V- inputs and RA2 as the V+ input to both comparators.

#### EXAMPLE 8-1: INITIALIZING COMPARATOR MODULE

FLAG_REG	F EQU	0X20
CLRF	FLAG_REG	;Init flag register
CLRF	PORTA	;Init PORTA
MOVF	CMCON,W	;Move comparator contents to W
ANDLW	0xC0	;Mask comparator bits
IORWF	FLAG_REG,F	;Store bits in flag register
MOVLW	0x03	;Init comparator mode
MOVWF	CMCON	;CM<2:0> = 011
BSF	STATUS, RPO	;Select Bank1
MOVLW	0x07	;Initialize data direction
MOVWF	TRISA	;Set RA<2:0> as inputs
		;RA<4:3> as outputs
		;TRISA<7:5> always read `0'
BCF	STATUS, RPO	;Select Bank 0
CALL	DELAY 10	;10µs delay
MOVF	CMCON, F	;Read CMCONtoend change condition
BCF	PIR1,CMIF	;Clear pending interrupts
BSF	STATUS, RPO	;Select Bank 1
BSF	PIE1,CMIE	;Enable comparator interrupts
BCF	STATUS, RPO	;Select Bank 0
BSF	INTCON, PEIE	;Enable peripheral interrupts
BSF	INTCON, GIE	;Global interrupt enable

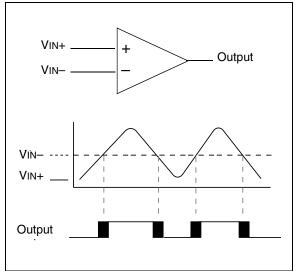
#### 8.2 Comparator Operation

A single comparator is shown in Figure 8-2 along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input VIN–, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input VIN–, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 8-2 represent the uncertainty due to input offsets and response time.

### 8.3 <u>Comparator Reference</u>

An external or internal reference signal may be used depending on the comparator operating mode. The analog signal that is present at VIN– is compared to the signal at VIN+, and the digital output of the comparator is adjusted accordingly (Figure 8-2).

FIGURE 8-2: SINGLE COMPARATOR



#### 8.3.1 EXTERNAL REFERENCE SIGNAL

When external voltage references are used, the comparator module can be configured to have the comparators operate from the same or different reference sources. However, threshold detector applications may require the same reference. The reference signal must be between VSS and VDD and can be applied to either pin of the comparator(s).

#### 8.3.2 INTERNAL REFERENCE SIGNAL

The comparator module also allows the selection of an internally generated voltage reference for the comparators. Section 13, Instruction Sets, contains a detailed description of the Voltage Reference Module that provides this signal. The internal reference signal is used when the comparators are in mode CM<2:0>=010 (Figure 8-1). In this mode, the internal voltage reference is applied to the VIN+ pin of both comparators.

#### 8.6 Comparator Interrupts

The comparator interrupt flag is set whenever there is a change in the output value of either comparator. Software will need to maintain information about the status of the output bits, as read from CMCON<7:6>, to determine the actual change that has occurred. The CMIF bit, PIR1<6>, is the comparator interrupt flag. The CMIF bit must be reset by clearing '0'. Since it is also possible to write a '1' to this register, a simulated interrupt may be initiated.

The CMIE bit (PIE1<6>) and the PEIE bit (INTCON<6>) must be set to enable the interrupt. In addition, the GIE bit must also be set. If any of these bits are clear, the interrupt is not enabled, though the CMIF bit will still be set if an interrupt condition occurs.

Note: If a change in the CMCON register (C1OUT or C2OUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CMIF (PIR1<6>) interrupt flag may not get set.

The user, in the interrupt service routine, can clear the interrupt in the following manner:

- a) Any read or write of CMCON. This will end the mismatch condition.
- b) Clear flag bit CMIF.

A mismatch condition will continue to set flag bit CMIF. Reading CMCON will end the mismatch condition, and allow flag bit CMIF to be cleared.

# 8.7 <u>Comparator Operation During SLEEP</u>

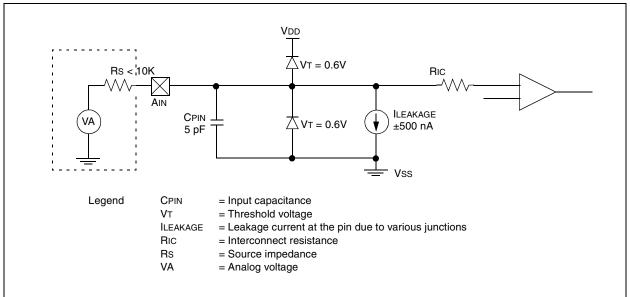
When a comparator is active and the device is placed in SLEEP mode, the comparator remains active and the interrupt is functional if enabled. This interrupt will wake-up the device from SLEEP mode when enabled. While the comparator is powered-up, higher sleep currents than shown in the power down current specification will occur. Each comparator that is operational will consume additional current as shown in the comparator specifications. To minimize power consumption while in SLEEP mode, turn off the comparators, CM<2:0> = 111, before entering sleep. If the device wakes-up from sleep, the contents of the CMCON register are not affected.

## 8.8 Effects of a RESET

A device reset forces the CMCON register to its reset state. This forces the comparator module to be in the comparator reset mode, CM<2:0> = 000. This ensures that all potential inputs are analog inputs. Device current is minimized when analog inputs are present at reset time. The comparators will be powered-down during the reset interval.

## 8.9 <u>Analog Input Connection</u> <u>Considerations</u>

A simplified circuit for an analog input is shown in Figure 8-4. Since the analog pins are connected to a digital output, they have reverse biased diodes to VDD and Vss. The analog input therefore, must be between Vss and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur. A maximum source impedance of 10 k $\Omega$  is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.



### FIGURE 8-4: ANALOG INPUT MODEL

# 10.0 SPECIAL FEATURES OF THE CPU

Special circuits to deal with the needs of real time applications are what sets a microcontroller apart from other processors. The PIC16CE62X family has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection.

These are:

- 1. OSC selection
- 2. Reset

Power-on Reset (POR) Power-up Timer (PWRT) Oscillator Start-Up Timer (OST) Brown-out Reset (BOD)

- 3. Interrupts
- 4. Watchdog Timer (WDT)
- 5. SLEEP
- 6. Code protection
- 7. ID Locations
- 8. In-circuit serial programming

The PIC16CE62X has a Watchdog Timer which is controlled by configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in reset until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only, and is designed to keep the part in reset while the power supply stabilizes. There is also circuitry to reset the device if a brown-out occurs, which provides at least a 72 ms reset. With these three functions on-chip, most applications need no external reset circuitry.

The SLEEP mode is designed to offer a very low current power-down mode. The user can wake-up from SLEEP through external reset, Watchdog Timer wake-up or through an interrupt. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost, while the LP crystal option saves power. A set of configuration bits are used to select various options.

#### 10.2 Oscillator Configurations

#### 10.2.1 OSCILLATOR TYPES

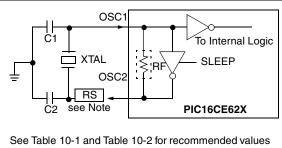
The PIC16CE62X can be operated in four different oscillator options. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

# 10.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation (Figure 10-1). The PIC16CE62X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1 pin (Figure 10-2).

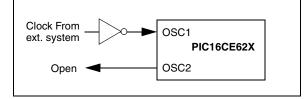
#### FIGURE 10-1: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (HS, XT OR LP OSC CONFIGURATION)



See Table 10-1 and Table 10-2 for recommended values of C1 and C2.

Note: A series resistor may be required for AT strip cut crystals.

### FIGURE 10-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)



#### TABLE 10-1: CERAMIC RESONATORS, PIC16CE62X

**Ranges Tested:** OSC2 Mode Freq OSC1 XT 455 kHz 68 - 100 pF 68 - 100 pF 15 - 68 pF 15 - 68 pF 2.0 MHz 4.0 MHz 15 - 68 pF 15 - 68 pF HS 10 - 68 pF 10 - 68 pF 8.0 MHz 16.0 MHz 10 - 22 pF 10 - 22 pF

These values are for design guidance only. See notes at bottom of page.

#### TABLE 10-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR, PIC16CE62X

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF

These values are for design guidance only. See notes at bottom of page.

- 1. Recommended values of C1 and C2 are identical to the ranges tested table.
- 2. Higher capacitance increases the stability of oscillator, but also increases the start-up time.
- 3. Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
- 4. Rs may be required in HS mode, as well as XT mode, to avoid overdriving crystals with low drive level specification.

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CLRWDT	Clear Watchdog Timer				
Syntax:	[ label ] CLRWDT				
Operands:	None				
Operation:	$\begin{array}{l} 00h \rightarrow WDT \\ 0 \rightarrow WDT \text{ prescaler,} \\ 1 \rightarrow \overline{TO} \\ 1 \rightarrow \overline{PD} \end{array}$				
Status Affected:	TO, PD				
Encoding:	00 0000 0110 0100				
Description:	CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.				
Words:	1				
Cycles:	1				
Example	CLRWDT				
	Before Instruction WDT counter = ? After Instruction WDT counter = 0x00 WDT prescaler= 0 TO = 1 PD = 1				
COMF	Complement f				
Syntax:	[label] COMF f,d				

COME	Complement				
Syntax:	[ label ] COMF f,d				
Operands:	$\begin{array}{l} 0\leq f\leq 127\\ d\in [0,1] \end{array}$				
Operation:	$(\overline{f}) \rightarrow (dest)$				
Status Affected:	Z				
Encoding:	00 1001 dfff ffff				
Description:	The contents of register 'f' are complemented. If 'd' is 0, the result is stored in W. If 'd' is 1, the result is stored back in register 'f'.				
Words:	1				
Cycles:	1				
Example	COMF REG1,0				
	Before InstructionREG1= $0x13$ After InstructionREG1= $0x13$ W= $0xEC$				

Decrement f				
[label] DECF f,d				
$0 \le f \le 127$				
d ∈ [0,1]				
(f) - 1 $\rightarrow$ (dest)				
Z				
00 0011 dfff ffff				
Decrement register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.				
1				
1				
DECF CNT, 1				
Before Instruction CNT = 0x01 Z = 0 After Instruction CNT = 0x00 Z = 1				
Decrement f, Skip if 0				
[ <i>label</i> ] DECFSZ f,d				
$0 \leq f \leq 127$				
d ∈ [0,1]				

Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$					
Operation:	(f) - 1 $\rightarrow$ (dest); skip if result = 0					
Status Affected:	None					
Encoding:	00	1011	dfff	ffff		
Description:	The contents of register 'f' are decremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'. If the result is 0, the next instruction, which is already fetched, is discarded. A NOP is executed instead making it a two-cycle instruction.					
Words:	1					
Cycles:	1(2)					
Example	HERE DECFSZ CNT, 1 GOTO LOOP CONTINUE • •					
	Before In PC After Inst CNT if CNT PC if CNT PC	= ado ruction = CN = 0, = ado ≠ 0,	iress HERE T - 1 iress CONT			

NOP	No Operation								
Syntax:	[ label ]	NOP							
Operands:	None								
Operation:	No operation								
Status Affected:	None								
Encoding:	0 0	0000	0xx0	0000					
Description:	No operation.								
Words:	1								
Cycles:	1								
Example	NOP								

RETFIE	Return from Interrupt							
Syntax:	[label] F	RETFIE						
Operands:	None							
Operation:	$TOS \rightarrow PC$ , 1 $\rightarrow GIE$							
Status Affected:	None							
Encoding:	0.0	0000	0000	1001				
Description:	Return from Interrupt. Stack is POPed and Top of Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two-cycle instruction.							
Words:	1							
Cycles:	2							
Example	RETFIE							
	After Intern PC Gl		TOS 1					

OPTION	Load Option Register						
Syntax:	[ label ] OPTION						
Operands:	None						
Operation:	$(W) \rightarrow OPTION$						
Status Affected:	None						
Encoding:	00 0000 0110 0010						
Description: Words: Cycles: Example	The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it. 1 1						
	To maintain upward compatibility with future PIC <sup>®</sup> MCU products, do not use this instruction.						

RETLW	Return with Literal in W
Syntax:	[ <i>label</i> ] RETLW k
Operands:	$0 \leq k \leq 255$
Operation:	$k \rightarrow (W);$ TOS $\rightarrow$ PC
Status Affected:	None
Encoding:	11 01xx kkkk kkkk
Description:	The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.
Words:	1
Cycles:	2
Example	CALL TABLE ;W contains table ;offset value ;W now has table value
TABLE	ADDWF PC ;W = offset RETLW k1 ;Begin table RETLW k2 ;
	RETLW kn ; End of table
	Before Instruction W = 0x07
	After Instruction W = value of k8

NOTES:

# 13.1 DC CHARACTERISTICS:

### PIC16CE62X-04 (Commercial, Industrial, Extended) PIC16CE62X-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS		$\begin{array}{llllllllllllllllllllllllllllllllllll$					
Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
D001	Vdd	Supply Voltage	3.0	-	5.5	V	See Figure 13-1 through Figure 13-3
D002	Vdr	RAM Data Retention Voltage (Note 1)	-	1.5*	-	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	-	Vss	-	V	See section on power-on reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	-	-	V/ms	See section on power-on reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current (Note 2, 4)	-	1.2	2.0	mA	Fosc = 4 MHz, VDD = 5.5V, WDT disabled, XT osc mode, (Note 4)*
			-	0.4	1.2	mA	Fosc = 4 MHz, VDD = 3.0V, WDT disabled, XT osc mode, (Note 4)
			-	1.0	2.0	mA	Fosc = 10 MHz, VDD = 3.0V, WDT disabled, HS osc mode, (Note 6)
			-	4.0	6.0	mA	Fosc = 20 MHz, VDD = 4.5V, WDT disabled, HS osc mode
			-	4.0	7.0	mA	Fosc = 20 MHz, VDD = 5.5V, WDT disabled*, HS osc mode
			-	35	70	μA	Fosc = 32 kHz, VDD = 3.0V, WDT disabled, LP osc mode
D020	IPD	Power Down Current (Note 3)	-	-	2.2	μA	VDD = 3.0V
			-	-	5.0	μA	VDD = 4.5V*
			_	-	9.0 15	μΑ μΑ	VDD = 5.5V VDD = 5.5V Extended
D022	ΔIWDT	WDT Current (Note 5)	- 1	6.0	10	μΑ	VDD = 4.0V
					12	μA	(125°C)
D022A	$\Delta$ IBOR	Brown-out Reset Current (Note 5)	-	75	125	μA	BOD enabled, VDD = 5.0V
D023	∆ICOMP	Comparator Current for each Comparator (Note 5)	-	30	60	μA	VDD = 4.0V
D023A	$\Delta$ IVREF	VREF Current (Note 5)	-	80	135	μA	VDD = 4.0V
	$\Delta \text{IEE Write}$	Operating Current	-		3	mA	Vcc = 5.5V, SCL = 400 kHz
	∆IEE Read	Operating Current	-		1	mA	
	ΔIEE	Standby Current	-		30	μA	$V_{CC} = 3.0V, EE V_{DD} = V_{CC}$
4.4	ΔIEE	Standby Current	-		100	μΑ	Vcc = 3.0V, EE VDD = Vcc
1A	Fosc	LP Oscillator Operating Frequency	0	-	200	kHz	All temperatures
		RC Oscillator Operating Frequency XT Oscillator Operating Frequency	0 0	_	4	MHz MHz	All temperatures All temperatures
		HS Oscillator Operating Frequency	0	_	4 20	MHz	All temperatures

These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

 $\overline{MCLR} = VDD$ ; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in k $\Omega$ .

5: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

**6:** Commercial temperature range only.

#### 13.2 DC CHARACTERISTICS: F

#### PIC16LCE62X-04 (Commercial, Industrial)

DC CHARACTERISTICS		$\begin{array}{llllllllllllllllllllllllllllllllllll$							
Param No.	Sym	Characteristic	Min Typ†		Max	Units	Conditions		
D001	Vdd	Supply Voltage	2.5	-	5.5	V	See Figure 13-1 through Figure 13-3		
D002	Vdr	RAM Data Retention Voltage (Note 1)	-	1.5*	-	V	Device in SLEEP mode		
D003	VPOR	VDD start voltage to ensure Power-on Reset	-	Vss	-	V	See section on power-on reset for details		
D004	SVDD	VDD rise rate to ensure Power-on Reset	.05*	-	-	V/ms	See section on power-on reset for details		
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared		
D010	IDD	Supply Current (Note 2)	-	1.2	2.0	mA	Fosc = 4 MHz, VDD = 5.5V, WDT disabled, XT osc mode, (Note 4)*		
			-	-	1.1	mA	FOSC = 4 MHz, VDD = 2.5V, WDT disabled,		
			-	35	70	μA	XT osc mode, (Note 4) Fosc = 32 kHz, VDD = 2.5V, WDT disabled, LP osc mode		
D020	IPD	Power Down Current (Note 3)	_	-	2.0	μA	VDD = 2.5V		
			-	-	2.2	μA	VDD = 3.0V*		
			-	-	9.0	μA	VDD = 5.5V		
			-	-	15	μA	VDD = 5.5V Extended		
D022	$\Delta$ IWDT	WDT Current (Note 5)	-	6.0	10	μA	VDD=4.0V		
D022A		Brown-out Reset Current	_	75	12 125	μΑ μΑ	$(125^{\circ}C)$ BOD enabled, VDD = 5.0V		
D023		(Note 5) Comparator Current for each Comparator (Note 5)	-	30	60	μA	VDD = 4.0V		
D023A	$\Delta$ IVREF	VREF Current (Note 5)	-	80	135	μA	VDD = 4.0V		
	$\Delta$ IEE Write	Operating Current	-		3	mA	Vcc = 5.5V, SCL = 400 kHz		
	$\Delta IEE \ Read$	Operating Current	-		1	mA			
	$\Delta IEE$	Standby Current	-		30	μA	VCC = 3.0V, EE VDD = VCC		
	$\Delta IEE$	Standby Current	-		100	μA	VCC = 3.0V, EE VDD = VCC		
1A	Fosc	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures		
		RC Oscillator Operating Frequency		—	4	MHz	All temperatures		
		XT Oscillator Operating Frequency	0	—	4 20	MHz	All temperatures		
		HS Oscillator Operating Frequency	-	_	20	MHz	All temperatures		

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kΩ.

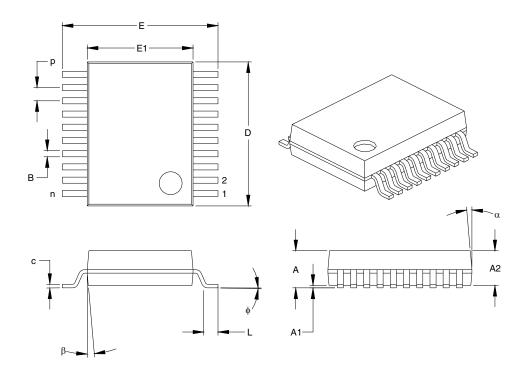
5: The  $\Delta$  current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

NOTES:

## 20-Lead Plastic Shrink Small Outline (SS) - 209 mil, 5.30 mm (SSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	INCHES*			MILLIMETERS		
Dimensior	MIN	MIN NOM		MIN	NOM	MAX	
Number of Pins	n		20			20	
Pitch	р		.026			0.66	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	С	.004	.007	.010	0.10	0.18	0.25
Foot Angle	¢	0	4	8	0.00	101.60	203.20
Lead Width	В	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

\*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MO-150

Drawing No. C04-072

NOTES:

#### Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
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